LIGENTEC

Photonic Integrated Circuits for Quantum Computing

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April 2021

Low loss SiN PICs



Photonic Integration Passive Components



LIGENTEC Offering Value chain





LIGENTEC Offering **Process Design Kit (PDK)**



LIGENTEC platform Couplers / MMIs: first time right possible







LIGENTEC platform Application specific process modules available







Quantum

- No moveable parts
 - Phase stability
- Small size components
 - Everything is integrated on a chip
- Scaling to volume
 - Same chip 1 Million times with wafer processing

Applications - Quantum Towards an optical quantum computer









Arrazola et al., Nature 54 March 2021

Applications - Quantum Towards an optical quantum computer



Spontaneous four wave mixing allows photon pair generation.



Vaidya et al., Science Advances 23 Sep 2020

Applications - Quantum Squeezed light from FWM on a chip

Spontaneous four wave mixing allows photon pair generation.



 $R \sim (\gamma P)^2 Q^3 L^{-2}$

Small-size, High-Q microring resonator is a key



LIGENTEC PROPRIETARY

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Custom Runs

- Can start any time
- Fast track options (6 weeks)
- Full choice of process modules
- Pilot runs to high volumes



"We are impressed with the device performance." USA customer

"We even got the chips before estimated shipping date." Canadian customer

Multi Project Wafer Runs

- AN800 (IR), AN150 (VIS)
- Preset process modules
- Fast (10 weeks)
- 4x per year, fixed dates
- Next run: March 2021 www.ligentec.com/Ligentec-foundry/



LIGENTEC Offering From prototype to production





Low Loss SiN - Platform Overview

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The Basics

- High Mode Confinement
- Low Loss
- Small Footprint
- High Power



Actives

- Electrical Tuning
- Modulators
- Lasers
- Detectors



Award winning PIC innovation from LiGenTec

LiGenTec focuses on silicon nitride for photonic integrated circuits





Full Creativity

- Couplers
- Mux / DeMux
- MZIs / DLIs
- Resonators

many more



World Connections

- Edge Coupling / U Grooves
- Spot Size Converter
- Grating Couplers
- Arbitrary Die Shape
- Bond pads



This project has received funding from the European Union's Horizon 2020 research and innovation programme under grant agreement #954530, #863322, #812818

Applications - Quantum SiN photonic controlled-NOT gate





Lee et al., ECOC paper 2020